

**DECLARATION FOR PATENT APPLICATION
AND POWER OF ATTORNEY**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below adjacent to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of subject matter (process, machine, manufacture, or composition of matter, or an improvement thereof) which is claimed and for which a patent is sought by way of the application entitled

ENCAPSULATION METHOD AND LEADFRAME OF LEADLESS SEMICONDUCTOR PACKAGE

- which (check) is attached hereto.
 and is amended by the Preliminary Amendment attached hereto.
 was filed on 28 March 2002 as Application Serial No. 10/113,526
 and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information, which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America listed below and have also identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed:

Prior Foreign Application(s)			Priority Claimed	
Number	Country	Day/Month/Year Filed	Yes	No
89118193	Taiwan, R.O.C.	06/09/2000	<input type="checkbox"/>	<input checked="" type="checkbox"/>
			<input type="checkbox"/>	<input type="checkbox"/>

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

Provisional Application Number	Filing Date

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) or PCT international application(s) designating the United States of America listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior application(s) in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information, which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56, which became available between the filing date of the prior application(s) and the national or PCT international filing date of this application:

Application Serial No.	Filing Date	Status (patented, pending, abandoned)

I hereby appoint the following practitioners to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith:

Customer Number 24251



Please direct all telephone calls to:

Telephone: 408-453-9200

I declare that all statements made herein of my own knowledge are true, all statements made herein on information and belief are believed to be true, and all statements made herein are made with the knowledge that whoever, in any matter within the jurisdiction of the Patent and Trademark Office, knowingly and willfully falsifies, conceals, or covers up by any trick, scheme, or device a material fact, or makes any false, fictitious or fraudulent statements or representations, or makes or uses any false writing or document knowing the same to contain any false, fictitious or fraudulent statement or entry, shall be subject to the penalties including fine or imprisonment or both as set forth under 18 U.S.C. 1001, and that violations of this paragraph may jeopardize the validity of the application or this document, or the validity or enforceability of any patent, trademark registration, or certificate resulting therefrom.

Full name of sole (or first joint) inventor: Frank Kuo

Inventor's Signature:

Date:

June 10, 2002

Residence: 8F, No. 30, Lin-Chuan St., Lin-Ya Dist., Kaohsiung City, Taiwan R.O.C.

Post Office Address: Same as above

Citizenship:

Taiwan, R.O.C.

Full name of second joint inventor:

Inventor's Signature:

Date:

Residence:

Citizenship:

Post Office Address:

Full name of third joint inventor:

Inventor's Signature:

Date:

Residence:

Citizenship:

Post Office Address:

Full name of fourth joint inventor:

Inventor's Signature:

Date:

Residence:

Citizenship:

Post Office Address:

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
Patent

In re Application of:

Inventor(s): Frank Kuo

Serial No.: 10/113,526

Filed: 03/28/02

Examiner:

Art Unit:

For: ENCAPSULATION METHOD AND LEADFRAME OF LEADLESS SEMICONDUCTOR PACKAGE
Patent No.: Issued Date:

Assistant Commissioner for Patents
Washington, D.C. 20231

**POWER OF ATTORNEY BY ASSIGNEE OF ENTIRE INTEREST
(REVOCATION OF PRIOR POWERS)**

As assignee of record of the entire interest of the above identified

- application,
 patent,

REVOCATION OF PRIOR POWERS OF ATTORNEY

all powers of attorney previously given are hereby revoked and

NEW POWER OF ATTORNEY

the following attorney(s) and/or agents(s) are hereby appointed to prosecute and transact all business in the Patent and Trademark Office connected herewith.

James P. Hao	Registration No.: 36,398
Anthony C. Murabito	Registration No.: 35,295
John P. Wagner	Registration No.: 35,398
Glenn D. Barnes	Registration No.: 42,293
Thomas M. Catale	Registration No.: 46,434
Jose S. Garcia	Registration No.: 43,628
Eric J. Gash	Registration No.: 46,274
Lin C. Hsu	Registration No.: 46,315
Ronald M. Pomerenke	Registration No.: 43,009
John F. Ryan	Registration No.: 47,050
Matthew J. Blecher	Registration No.: 46,558
Lawrence R. Goerke	Registration No.: 45,927
Reginald A. Ratliff	Registration No.: 48,098
William A. Zarbis	Registration No.: 46,120

Mehlin Dean Matthews Registration No.: 46,127
Joel D. Youngs Registration No.: 52,389
Michael R. Hardaway Registration No.: P-52,992

SEND CORRESPONDENCE TO:

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DIRECT PHONE CALLS TO:

Anthony C. Murabito
(408) 938-9060

Siliconix Taiwan Ltd.
(type or print identity of assignee of entire interest)

No. 3-3, East 2nd., Nan-Tzu
Export Processing Zone
Kaohsiung City, Taiwan R.O.C.
Address

- Recorded in PTO on 07/08/02
Reel 013065
Frame 0642
- Recorded herewith

ASSIGNEE CERTIFICATION

Attached to this power is a "CERTIFICATE UNDER 37 CFR 3.73(b)."

Date

7/31/03

Signature

Dr. King Owyang
(type or print name of person authorized to sign on behalf
of assignee)

President and CEO
Title

INSTRUCTIONS

US-4123

ASSIGNMENT OF U.S. RIGHTS TO CORPORATION

WHEREAS.

1. Frank Kuo residing at 8F, No. 30, Lin-Chuan St., Lin-Ya Dist., Kaohsiung City, Taiwan, R.O.C. and a citizen of Taiwan, R.O.C.
2. _____ residing at _____ and a citizen of _____
3. _____ residing at _____

and a citizen of _____; (herein called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States on Taiwan, R.O.C. for this invention, which application is entitled ENCAPSULATION METHOD AND LEADFRAME OF LEADLESS SEMICONDUCTOR PACKAGE and which has been given Serial Number 10/113,526 and the filing date of 28 March 2002;

AND WHEREAS Siliconix Taiwan Ltd. (herein called "ASSIGNEE"), a corporation organized under the laws of Taiwan, R.O.C. and having an office and place of business at No. 3-3, East 2nd Street, Nan-Tzu Export Processing Zone, Kaohsiung City, Taiwan, R.O.C. wishes to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of the sum of One Dollar and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign and transfer to the ASSIGNEE, its successors and assigns, the entire right, title and interest for the United States in and to the invention disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents to issue any and all United States Letters Patent for the aforesaid invention to the ASSIGNEE of the entire right, title and interest in and to the same, for the use of the ASSIGNEE, its successors and assigns.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to THE UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEE, its successors, or assigns the entire right, title and interest in and to the said invention, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEE, its successors and assigns, that no assignment grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by THE UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by THE UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.

Each Inventor
Must Sign
and Date

Signature Frank Kuo

Date

June 10, 2002

Note: No
Legalization or
Other Witness
Required

Signature

Date

Signature

Date